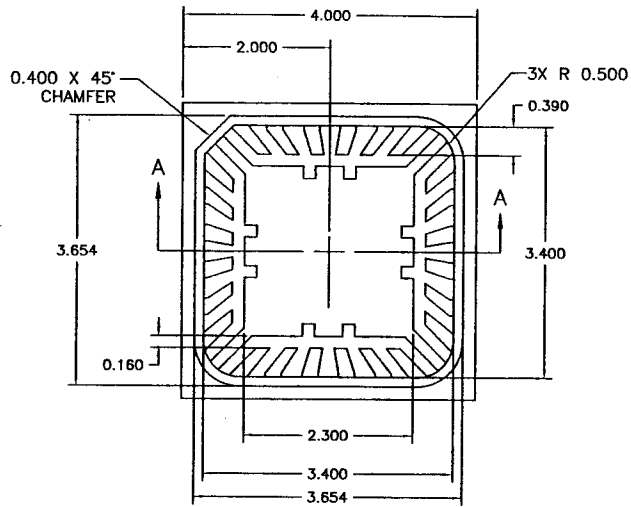
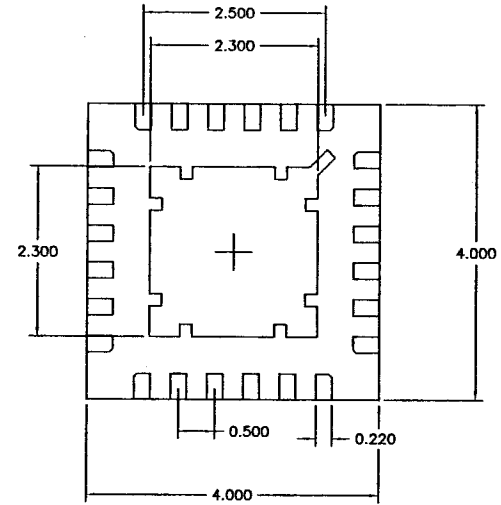
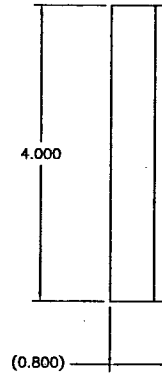


# SSM P/N: QFN02401

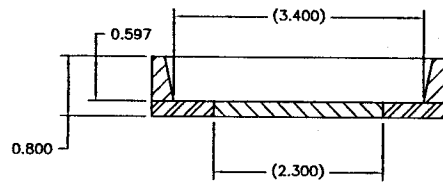
REVISIONS			
ECN NO.	DATE	DESCRIPTION	APPROVED
		PRODUCTION RELEASE	



TOP VIEW



BOTTOM VIEW



SECTION A-A

NOTES:

1. BODY: PLASTIC, SEMICONDUCTOR GRADE.
2. LEAD FRAME: COPPER, 194 FH.
3. LEAD FINISH: FULL GOLD PLATE.
4. FRAME THICKNESS: 0.2030 ± 0.0076.
5. DIE PAD: 2.300mm X 2.300mm.
6. JEDEC OUTLINE: MQ-220 (VGGD-2)

<p>THIRD ANGLE PROJECTION</p>	DRAWN BY	DATE
	APP BY	DATE
<p>UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN MILLIMETERS TOLERANCES ARE: X.XX ± 0.015 X.XXXX ± --- X.XXX ± 0.050 ANGLES: ± 1°</p>	CUSTOMER	---
DO NOT SCALE DRAWING		

24 Lead 4mm x 4mm

**QFN4X4-024 REV 2**

